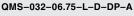


Integral metal plane

for power or ground





QMS SERIES

(0.635 mm) .025"

GED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:

Liquid Crystal Polymer Terminal & Ground Plane Material:

Phosphor Bronze

Plating: Au over 50 μ" (1.27 μm) Ni (Tin on Ground Plane Tail) Current Rating:

Contact: 2.6 A per pin (2 pins powered) Ground Plane:

15.7 A per ground plane

(1 ground plane powered)
Operating Temp:
-55 °C to +125 °C
Voltage Rating:
300 VAC mated with QFS **RoHS Compliant:**

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (026-052) (0.15 mm) .006" max (078)* (.004" stencil solution may be available; contact IPG@samtec.com)

Board Stacking:

For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



STANDARDS

- SUMIT
- PCI/104-Express[™]

PROTOCOLS

- 100 GbF
- Flbre Channel
- XAUI
- PCI Express®
- SATA

Some lengths, styles and options are non-standard, non-returnable

Board Mates:

Cable Mates:

Standoffs: SO. JSOM

QMS

ALSO AVAILABLE (MOQ Required)

- · Other platings
- **Guide Posts**
- Without PCB Alignment Pins (05.75 and 06.75 only)
- Hot Pluggable
- 64 (-DP) and 104 positions per row

Contact Samtec.

************ ecococcesses HIGH-SPEED CHANNEL PERFORMANCE

Increased

(1.60 mm) .063" NOMINAL insertion depth for WIPE rugged applications

POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

PINS PER ROW

NO. OF PAIRS

QMS-DP/QFS-DP @ 10 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

LEAD

STYLE

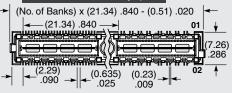
PLATING OPTION

OTHER OPTION

-026, -052, -078 (52 total pins per bank = -D)

–016, –032, –048 (16 pairs per bank = -D-DP)

(-078 & -048 Not available with -09.75 lead style)



MATED HEIGHT*

*Processing conditions will affect mated height. See SO Series for board space tolerances.

-04.25

10 mm

11 mm

14 mm

LEAD

STYLE

-05.75 (5.38) .212

-06.75 (6.35) .250

-09.75 (9.35) .368

-D-DP

QFS LEAD STYLE

Specify LEAD STYLE from chart

–05.75 and –06.75 lead style only) = 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

-SL

(-09.75 lead style only) = 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)

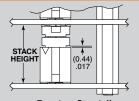


–D = Single-Ended

-D-DP = Differential Pair

-K (5.50 mm) .217" DIA Polyimide film Pick & Place Pad

APPLICATION



Requires Standoff SO-1524-03-01-01-L or JSOM-1524-02 for 15.24 mm or SO-2215-02-01-01-L for 22 mm board spacing. Connectors designed to not fully seat when mated.

INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15.24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15.24 mm
PCI/104-Express™	ASP-129637-13	ASP-129646-22	1	15.24 mm
PCI/104-Express™	ASP-142781-01	ASP-129646-01	1	22 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm

Due to technical progress, all designs, specifications and components are subject to change without notice

-06.25

12 mm

13 mm

16 mm